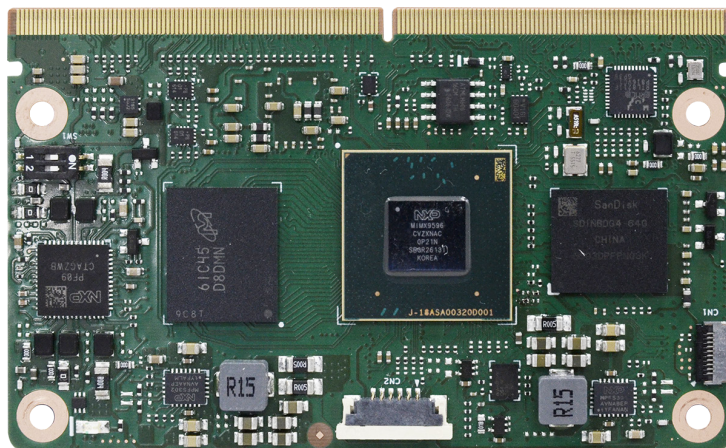
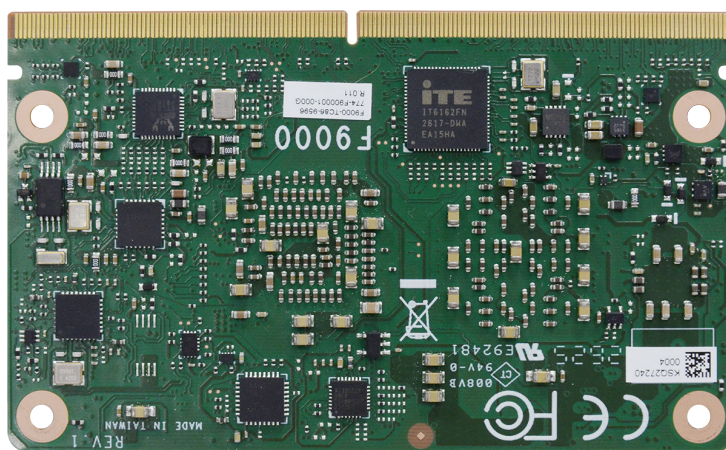


F9000

NXP i.MX95 Processor
SMARC



Top View



Bottom View

KEY FEATURES



NXP iMX95

Up to 6 Arm Cortex
A55 cores



LPDDR5

4/8GB LPDDR5
Memory Down



Display Options

1 Dual channel LVDS,
1 HDMI



Multiple Expansion

2 PCIe 3.0, 1 SDIO 3.0,
1 I2C, 2 SPI, 4 UART,
2 CAN bus, 1 MIPI CSI



Rich I/O

2 GbE LAN, 1 USB OTG,
1 USB 3.2, 5 USB 2.0

SPECIFICATION

SYSTEM	Processor	NXP i.MX95 series up to 6 Arm Cortex A55 cores, up to 2.0GHz	
	Memory	4/8GB LPDDR5-6400 Memory Down	
GRAPHICS	Controller	Arm® Mali™ G310 GPU	
	Feature	OpenGL ES 3.2 Vulkan 1.2, OpenCL 3.0	
	Display	1 x Dual channel LVDS (default) 1 x HDMI (BOM option)	
EXPENSION	Interface	2 x PCIe Gen3 x1 1 x SDIO 3.0 1 x I2C 2 x SPI 2 x 4-wire UART and 2 x 2-wire UART 2 x CAN bus 1 x 4-lanes MIPI CSI (default), or optional 1x 2-lanes MIPI CSI	
AUDIO	Interface	1 x I2S	
ETHERNET	Controller	2 x 10/100/1000Mbps GbE	
I/O	USB	1 x USB OTG (default), or 1 x USB 2.0 1 x USB3.2 Gen2 x1 4 x USB 2.0 thru USB hub	
	eMMC	Supports eMMC 5.1, BGA-153 Ball up to 128GB	
	GPIO	1 x 14-bit GPIO	
SECURITY	TPM	TPM 2.0	
POWER	Type	5V DC-In	
	Consumption	TBD	
OS SUPPORT	OS Support	Linux Yocto	
ENVIRONMENT	Temperature	Operating: -40 to 85°C	
	Humidity	Operating: 5 to 90% RH	Storage: 5 to 90% RH
	MTBF	TBD	
MECHANISM	Dimensions	SMARC form factor	82 mm (3.23") x 50 mm (1.97")
	Compliance	SMARC specification revision 2.2 compliance	
STANDARDS AND CERTIFICATIONS	Certifications	CE, FCC, RoHS	

ORDERING INFORMATION

Model Name	P/N	CPU Cores	Memory	Display	TPM	USB 2.0	eMMC	Operating Temp.
F9000-TC86-9596	770-F900001-000G	6	8GB	LVDS	1	5	64GB	-40 to 85°C

PACKING LIST

• 1 F9000 board
• Cooler A71-108320-000G

OPTIONAL ITEMS

• SMARC Carrier Board SMX331
• Heat spreader